

Annual Report 2023



Publisher

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1 Preface

Dear friends of the Institute for Large Area Microelectronics,

We are pleased to present our activities and news of the year 2023 to our scientific cooperation partners, alumni and all our other friends.

In 2023, the institute could offer all the usual courses without any restrictions. Due to the increased efforts of the Department of Electrical Engineering and Information Technology towards internationalization, the institute is currently working on expanding the number of courses offered in English language. The focus is primarily on the translation of the module "Fundamentals of Electrical Engineering I/II".

In 2023, the joint research projects with IGM participation already mentioned in the last annual report were successfully continued. These are, in addition to a state-funded project in cooperation with an institute of the KIT (Karlsruhe Institute of Technology) for the demonstration of an additive assembly technology based on the UPD printer for an automotive radar that operates at 140 GHz, an EU-funded consortium for the production of micro LED displays as well as a BMBF consortium for the integration of liquid crystal based reconfigurable, intelligent surfaces for future 6G mobile networks. Furthermore, the already ongoing research work for the development of quantum-based gas sensors will be continued within the Research Training Group "Photonic Quantum Engineers" (GRK2642).

I would like to thank all friends of the institute for their support and inspiration and wish you all ongoing good health.

A special thank you to all employees for their tireless commitment ensuring the successful work of the institute on a daily basis. I also sincerely wish you and your families' health, happiness and all the best.

Stuttgart, April 2023

Prof. Dr.-Ing. Norbert Fruehauf

2 The Institute

The Institute for Large Area Microelectronics (IGM) is a research and education institute with a major focus on application-oriented research and development of new processes and materials for applications in display technologies.

With its more than 500m² of clean room area the Institute of Large Area Microelectronics operates one of the leading independent laboratories for the research and development of thin film electronics and thin film technology (TFTs) as well as their respective fields of application, e.g.:

- Flat panel displays (LCD, OLED)
- Smart Glass
- Optical signal processing
- Micro-electro-mechanical systems (MEMS)

The laboratory has always been focused on application-oriented research and portability to industrial grade production. Therefore, the clean room lab was designed to build complete active matrix LCDs on glass substrates of up to 16 inches squared. This capability to process such (relatively, for a research facility) large substrates gives the laboratory at the Institute for Large Area Microelectronics a unique position in all of Europe.

Besides the extensive research activities of the institute, the university teaching plays an important role. In teaching, the institute represents the fundamentals of electrical engineering as well as display and thin film technologies.

3 Staff Members

Function	Name	E-mail @igm.uni- stuttgart.de	Phone +49 711 685-
Head of Institute	Prof. DrIng. Norbert Fruehauf	norbert.fruehauf	66922
Vice Head of Institute/ Head of Laboratory	DiplIng. Lothar Rau	lothar.rau	66927
Vice Head of Laboratory	DiplIng. Holger Baur	holger.baur	66926
Secretary	Birgit Schuder	birgit.schuder	66922
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4 Teaching

Professor Fruehauf offers lectures on fundamentals of electrical engineering, filter synthesis, optical signal processing, thin film technology and flat panel technology. Several lab courses allow the students to gain some hands-on experience complementing the lectures.

4.1 Lectures

All lectures are recorded and uploaded on ILIAS to give the best possible support to the students.

Fundamentals of Electrical Engineering 1

Lecturer: Prof. Dr.-Ing. Norbert Fruehauf

Winter semester, 1 semester, 1st semester Bachelor's program Electrical Engineering & Information Technology, Mechatronics and Renewable Energies

- Introduction and overview
- Voltage and electric current
- Ohm's Law
- Electric power
- Kirchhoff's Laws
- Network analysis
- Electric field
- Capacities
- Magnetic field
- Induction Law

Fundamentals of Electrical Engineering 2

Lecturer: Prof. Dr.-Ing. Norbert Fruehauf

Summer semester, 1 semester, 2nd semester Bachelor's program Electrical Engineering & Information Technology, Mechatronics and Renewable Energies

- Inductances
- Sinusoidally alternating quantities
- Circuits at alternating currents
- General two-poles
- Modulated sources
- Resonant circuits

The two-semester module "Fundamentals of Electrical Engineering" consists of:

- Weekly lecturers
- Bi-weekly lecture exercises
- Bi-weekly group exercises (Electrical Engineering & Information Technology B.Sc. and Renewable Energies B.Sc.: winter semester compulsory, Mechatronics B.Sc.: winter **and** summer semester compulsory)
- Lab course "Fundamentals of Electrical Engineering" (compulsory)

Important notice:

The module examination "Fundamentals of Electrical Engineering" is a middegree exam of Electrical Engineering and Information Technology B.Sc. The right for examination expires if the mid-degree exam is not passed until beginning of the 4th semester (inclusive a written retry).

Filter Synthesis

Lecturer: Prof. Dr.-Ing. Norbert Fruehauf

Winter semester, 1 semester, Master's program

- Introduction
- Mathematics foundations
- RLC-Two-Poles
- Realization of filters
- Transformation of RLC-circuits into active RC-circuits
- Synthesis of reactance four-poles
- RC-active circuits
- Synthesis of distributed circuits of grade two
- Empfindlichkeitstheorie
- Optimization of distributed circuits
- Switched Capacitor Filter

Thin Film Technology

Lecturer: Prof. Dr.-Ing. Norbert Fruehauf

Winter semester, 1 semester, Master's program. This lecture is only available in English.

- Introduction and overview
- Vacuum thin film technology: vacuum technology, vapor deposition, sputtering, plasma deposition, growth and properties of thin films
- Non-vacuum deposition: spin coating, printing, chemical deposition
- Materials for substrates and surface treatment
- Structuring of thin films
- Metrology

Flat Panel Displays

Lecturer: Prof. Dr.-Ing. Norbert Fruehauf

Summer semester, 1 semester, Electrical Engineering and Information Technology B.Sc. / Photonic Engineering M.Sc.

- Overview: cathode ray tubes, flat panel display technologies, current technologies
- Physiology of sight: color theory, CIE 1931 color space, color filters
- Fundamentals of liquid crystal technology: electro-mechanical properties, variation of the potential energy, twisted and non-twisted lc cells
- Light propagation in optically anisotropic uni-axial media: Jones vectors, Jones matrices
- Liquid crystal technologies: optical transmission through the Fréedericksz cell, vertically aligned and twisted nematic lc cells, surface stabilized ferro electric lc cells
- Control of lc cells: direct addressing, passiv matrix, active matrix

Optical Signal Processing

Lecturer: Prof. Dr.-Ing. Norbert Fruehauf

Summer semester, 1 semester, Master's program. This lecture is only offered in English.

- Mathematic description of optical signals and optical systems
- Analogue optical signal processing: Fourier-transformation of optical signals, optical filters
- Optical storage: CD, DVD, Blu-Ray, holography
- Optical sensors
- Digital optical signal processing

Organic Transistors

Lecturer: Dr. Hagen Klauk

Winter semester, 1 semester

- Overview: applications for organic transistors, economical considerations, realizations and general properties of organic transistors
- Electronic properties of conjugated carbohydrates: localized and delocalized molecular orbitals, energy of orbitals
- Electronic properties of organic solid state structures: crystalline structure, diesperion, charge transport in partially crystalline layers
- Structure and implementation of organic transistors: selection of materials, stack and processing
- Functionality of organic transistors: channel, carrier injection, band model, analytical description of the characteristics
- Frequency dependence of organic transistors: analysis and optimization of the frequency limit
- Applications for organic transistors: flat panel displays, integrated circuits

4.2 Exercises

Fundamentals of Electrical Engineering 1 and 2 – Lecture Exercises

Contact person: Dr.-Ing. Patrick Schalberger Winter and summer semester, 2 semesters, Bachelor's program

Fundamentals of Electrical Engineering 1 and 2 – Group Exercises

Contact person: Dr.-Ing. Patrick Schalberger Winter and summer semester, Bachelor's program Winter semester compulsory for Electrical Engineering & Information Technology B.Sc. and Renewable Energies B.Sc. Winter **and** summer semester compulsory for Mechatronics B.Sc.

Filter Synthesis Exercises

Contact person: Marco Dettling, M.Sc. Winter semester, 1 semester, Master's program

Thin Film Technology Exercises

Contact person: Hanghang Li, M.Sc. Winter semester, 1 semester, Master's program The exercises are only available in English

Flat Panel Displays Exercises

Contact person: Kai Waldner, M.Sc. Summer semester, 1 semester, Electrical Engineering & Information Technology B.Sc. and Photonic Engineering M.Sc.

Optical Signal Processing Exercises

Contact person: Yannick Schellander, M.Sc. Summer semester, 1 semester, Master's program The exercises are only offered in English

4.3 Lab Courses

Lab Course "Fundamentals of Electrical Engineering"

The lab course is an inter-institutional course and takes place in the second semester (summer semester). It is compulsory for Electrical Engineering and Information Technology B.Sc. and for Renewable Energies B.Sc.

In addition to demonstrating and reinforcing basic concepts of electrical engineering, including "capacities as blocks to direct currents", "basic circuits with transistors", and "simple voltage dividers using resistors", the experiment "transistor-based amplifier" in the lab course is designed to teach practical experience in the implementation and testing of an amplifier cuircuit using bipolar transistors. The students will build the circuit, expanding it step by step and testing the behavior. The resulting circuit will feature a photo-transistor to create a infrared receiver. Using a transmission circuit also built during the experiment, an audio signal can be transmitted wireless.

Advanced Lab Course "Flat Panel Displays"

The lab course is part of the Master's program and takes place as an oneweek block course during the first week after the end of lecture period in the summer semester.

This lab course "Flat Panel Displays" focuses on the building of a display for a digital clock. This display is based on a seven-segment display with liquid crystals, polarizers, implemented on glass substrates. All processing steps, including sputtering ITO, spin coating with photo resist and poluimide, photo lithography, wet chemical structuring, and cell construction are performed by the participants in the clean room at the Institute for Large Area Microelectronics. Finally, the display is connected to an IC to form a simple alarm clock. The participants can retain the clock they have built.

Advanced Lab Course "Optical Signal Processing"

The lab course "Optical Signal Processing" is part of the Master's program and takes place in the winter semester during the lecture period. Students will perform experiments on topics including:

- Spatial and temporal coherence
- Collimation (homogenous plane waves)
- Imaging and Refraction
- Diffraction
- Fourier Optics
- Design and production of synthetic holograms

4.4 Degrees and Awards

The following Bachelor's, Research and Master's theses were successfully passed in 2022:

Bachelor's theses

Daniel Ruedt

Alternative Drain-/Source-connection for IGZO transistors

André Glaser

Investigation of drive concepts for large area sensor arrays

Research theses

Nishika Agrawal

Compatibility of a-Si photo diodes with IGZO thin film transistors

Nora Loesch

Optimization of Sintering and Deposition Processes for Extremely Precise Printing of Highly Conductive Nano Materials

Anant Mantha

Investigation of dielectrics in MEMS devices

Nishitha Palan

Investigation of Photoresist Stacking for Hybrid Capillary-Based 3D Microelectronic Devices

Research theses

Arpan Biswas

Automated Extraction of TFT Parameters for Simulation

Shreya Pervaje

Development and production of UV photosensors and photocurrent detection with a-IGZO

Master's theses

Markus Widmaier

Investigation of Plasma Deposited Thin Films for MEMS Devices

Yunyi Ouyang

Investigation of IGZO-TFTs with small width/length

Xiaoge Bai

Investigation of IGZO transistor behavior with separately connected top- and bottom-gates

Nishika Agrawal

Analog-to-digital converter circuits with indium-gallium-zinc-oxide thin-film transistors

Leo Burger Robust IGZO analog circuits

Maurice Schamber

Application of IGZO semiconductors for UV photo detection The master's thesis was supervised together with Prof. Dr. Tilmann Pfau, Head of 5th Institute of Physics.

Award

SID Distinguished Student Paper Award

Yannick Schellander, PhD student at IGM, gave a presentation entitled "Ultraviolet Photodetectors and Readout Based on a-IGZO Semiconductor Technology" at the SID Display Week 2023 on May 25, 2023 and was awarded the "Distinguished Student Paper Award" together with Marius Winter, Maurice Schamber, Fabian Munkes, Patrick Schalberger, Harald Kuebler, Tilman Pfau and Norbert Fruehauf.

The International Symposium took place from 21st to 26 May 2023 in Los Angeles, USA. An extended version of the paper was published in the "Journal of the Society for Information Display".

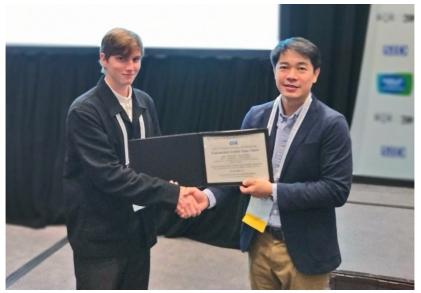


Fig. 1: The "SID Distinguished Student Paper Award" is handed over to Yannick Schellander

Certificate of Commendation

Prof. Norbert Fruehauf and Dr. Patrick Schalberger were awarded the "Certificate of Commendation" for their outstanding work as General Chair and Program Chair of the Eurodisplay 2022 in Stuttgart, Germany. Both awards were handed over to Prof. Norbert Fruehauf at the SID Display Week 2023 in Los Angeles, USA in May 2023.



Fig. 2 Achin Bhowmik, SID President, hands over the "Certificate of Commendation" to Norbert Fruehauf

5 **Projects and Research Activities**

Most research activities are third party funded. In addition to federal and European research grants, close cooperations with numerous industrial partners in Germany, Europe, but also in North America and Asia are important sources for funding and projects. Especially German companies profit from the extensive research activities at the Institute for Large Area Microelectronics allowing them to build their own know-how in the field of flat panel displays in a field that is otherwise dominated by companies from Asia.

The institute is currently doing research work on the following projects:

5.1 WAGNER-Project

The WAGNER-project, funded by the MWK Baden-Wuerttemberg, has the goal to develop an electronic packaging for an automotive radar that operates at 140 GHz that is fabricated by the Ultra-Precise Deposition (UPD) printing system. Recently introduced by XTPL, the UPD printer works by extruding a highly viscous ink through a very thin nozzle that is in contact with the substrate. This approach has unmatched precision and resolution for an additive process. The high precision enables UPD's use for fabricating waveguides, which are necessary for a functional chip interconnect at sub-THz frequencies. The framework of the InnovationCampus Future Mobility (ICM), of which WAGNER is a part of, has also led to extensive networking with several institutes of the University of Stuttgart and the Karlsruhe Institute of Technology (KIT).

5.2 Research Training Group (GRK2642): Quantum Sensor

New Readout Concepts for the Electrical Readout of Optogalvanic Nitric Oxide Trace Gas Sensors

A trace gas sensor based on an optogalvanic detection of Rydberg states should allow the detection of nitric oxide (NO) in the low ppb range in a background vapor at atmospheric pressure. NO molecules in gas cells are excited to Rydberg states and subsequently ionized by collisions with the background gas. The charges are guided to electrodes and detected by current measurements. The electrical readout can outperform optical detection in terms of sensitivity and integration time. Thin film technology can be used to realize the electrical readout (electrode + transimpedance amplifier) on the vapor cell wall.

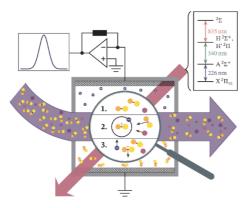


Fig. 3: Schematic operation principle for Rydberg based optogalvanic trace gas sensing

5.3 Industry funded Project "Photo Sensors"

Requested by a Japanese start up company the IGM develops a large area photo sensor array. Special challenges within this project are the requested area of the sensor array of more than 100cm² as well as the target to keep the array substantially transparent. Furthermore, the manufacture of the array shall take place using well established methods of large area microelectronics thus enabling the inexpensive mass production in fabrication lines for flat panel displays.

5.4 BAMBAM-Project

The EU funded project "BAMBAM" (<u>Building Active MicroLED displays By</u><u>A</u>dditive <u>M</u>anufacturing) started in September 2022. The goal is to develop innovative manufacturing methods for the future production of greener displays in Europe. The consortium consists of partners located all over Europe: Aledia (France), Xdisplay and X-Celeprint (Irleand), BARCO and QustomDot (Belgium), XTPL (Poland) and the Institute for Large Area Microelectronics of the University of Stuttgart (Germany). The focus of research at IGM for the project is on electrical contacting of Micro LEDs and driver ICs by a new, high resolution printing method (Ultra-Precise Deposition) developed by XTPL as well as on manufacturing of additional functional structures in the display.

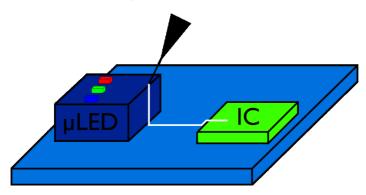


Fig. 4: Contacting of Micro LED and driver IC on pixel level by UPD printing

5.5 6G-LICRIS-Project

In October 2022, the BMBF funded joint research project 6G-LICRIS (Liquid Crystal Reconfigurable Intelligent Surfaces for 6G Mobile Networks) has been started. Consortium partners are Rohde & Schwarz, Ericsson, Merck, IMST, brown-iposs, Fraunhofer HHI, TU Berlin and the IGM oft the University of Stuttgart. Research topic is the integration of liquid crystal based intelligent, reflective surfaces in future 6G mobile networks. The RIS (Reconfigurable Intelligent Surfaces) shall improve network coverage by controlled reflection of radio waves and reduce power consumption compared to the usage of repeaters. The working principle is comparable to a two dimensional phased array antenna, where the phase difference between the single elements is influenced by locally controlling the orientation of liquid crystal molecules. First tasks of IGM are development and optimization of manufacturing processes for the LC based RIS elements and integration with an adapted (active) matrix technology. This is followed by the development of a dedicated addressing system and finalized by realization of complete RIS modules at IGM for characterization and network demonstrator integration at the project partners sites.

6 Invited Talks and Conferences

May 25, 2023: Presentation at the SID Display Week 2023 in Los Angeles, USA

Yannick Schellander, PhD student at IGM, gave a presentation entitled "Ultraviolet Photodetectors and Readout Based on a-IGZO Semiconductor Technology" at the SID Display Week 2023 on May 25, 2023 and was awarded the "Distinguished Student Paper Award" together with Marius Winter, Maurice Schamber, Fabian Munkes, Patrick Schalberger, Harald Kuebler, Tilman Pfau and Norbert Fruehauf. The International Symposium took place from 21st to 26 May 2023 in Los Angeles, USA. An extended version of the paper was published in the "Journal of the Society for Information Display".

August 23, 2023: Invited talk at the IMID 2023 in Busan, Korea

On August 23, 2023, Prof. Fruehauf gave an invited presentation entitled "Process and Circuit Designs for Co-Fabricated Enhancement and Depletion IGZO Thin Film Transistors" at the conference "International Meeting on Information Display (IMID)" which took place from August 22 to 25, 2023 in Busan, Korea. The presentation was created in cooperation with the co-authors Yannick Schellander, Hanghang Li and Florian Kleber.

December 6, 2023: Invited talk at the IDW '23 in Niigata, Japan

On December 6, 2023, Yannick Schellander, PhD student at the IGM, gave an invited talk entitled "Ultraviolet Photodetectors and their Readout Realization for Future Active Matrix Sensing" at the conference "International Display Workshop (IDW)" which took place from December 6 to 8, 2023 in Niigata, Japan. The presentation was created in cooperation with the coauthors Maurice Schamber, Fabian Munkes, Robert Loew, Patrick Schalberger, Harald Kuebler, Tilman Pfau, Norbert Fruehauf.

7 **Publications**

Ultraviolet photodetectors and readout based on a-IGZO semiconductor technology

Schellander, Y., Winter, M., Schamber, M., Munkes, F., Schalberger, P., Kuebler, H., Pfau, T., Fruehauf, N.

Journal of the Society for Information Display, 2023, Vol. 31, Issue 5, pp. 363-372 <u>https://doi.org/10.1002/jsid.1202</u>

High-performance MEMS shutter display with metal-oxide thin-film transistors and optimized MEMS element

Nusayer, S.A.A., Schalberger, P., Baur, H., Kleber, F., Fruehauf, N. Journal of the Society for Information Display, 2023, Vol. 31, Issue 9, pp. 535-547 <u>https://doi.org/10.1002/jsid.1252</u>

Ultraprecise Printing of D-Band Transmission Lines

Roemhild, M., Gramlich, G., Baur, H., Zwick, T., Fruehauf, N.) *IEEE Microwave and Wireless Technology Letters, 2023, Vol. 33, Issue 10, pp. 1419-1422* <u>https://doi.org/10.1109/LMWT.2023.3300569</u>

A Diamond Quantum Magnetometer Based on a Chip-Integrated 4-way Transmitter in 130-nm SiGe BiCMOS

Lotfi, H., Kern, M., Striegler, N., Unden, T., Scharpf, J., Schalberger, P., Schwartz, I., Neumann, P., Anders, J. 2023 IEEE Radio Frequency Integrated Circuits Symposium (RFIC), pp. 253-256 https://doi.org/10.1109/RFIC54547.2023.10186184

Ultra-Precise Deposition (UPD) Printing for Millimeter Wave Interconnects in D-Band

Gramlich, G., Römhild, M., Baur, H., Bhutani, A., Lemmer, U., Fruehauf, N., Zwick, T.

2023 Asia-Pacific Microwave Conference (APMC). pp. 1-3 (2023) https://doi.org/10.1109/APMC57107.2023.10439807

8 Contribution to Organizations

- Chairman of the Board of Curators, Eduard-Rhein-Foundation, Germany
- Member of the Board of Curators, Institute for Microelectronics Stuttgart (IMS), Germany
- Regional Vice President Europe, SID Society of Information Display
- Member Active Matrix Committee, SID Society of Information Display
- Associate Editor, Journal of the Society of Information Display (JSID)
- Program Committee Member, AM-FPD, Japan
- Overseas Advisor, International Display Workshop (IDW), Japan

9 The Clean Room

The Institute for Large Area Microelectronics (IGM) possesses one of the largest university-based clean rooms for flat screen displays and similar systems in the world.

The facilities at the IGM include more than $500m^2$ clean room space. The majority of that area or about $480m^2$ are the main lab with a very high purity class for a research fertility (ISO5, less than 100 particles with a size of more than 0,5µm per cubic foot of air; ISO 4, less than 10 particles with a size of more than 0,5µm per cubic foot of air, in the area with the lithographic devices). The IGM is fully equipped to produce flat screens and similar thin film devices in near-industrial processes. The close similarity of the equipment and processes to industrial facility supports the technology transfer to industrial production lines.

A second, smaller clean room contains 3 MBraun glove boxes with a nitrogen inert atmosphere for the processing of organic semiconductors which are very sensitive to oxygen and humidity.

The following devices and facilities are available at the IGM:

Layer Deposition

 PECVD: The IGM features several PECVD reactors, including one Balzers (Oerlikon) KAI 1M reactor for the deposition of amorphous or polycrystalline silicon (including doping), silicon nitrate, and silicon oxide on glass substrates up to 16 inches squared.

- **Sputtering:** Two Leybold ZV6000 inline-sputtering systems equipped with a total of 12 different targets (9 DC and 3 RF) are available at the IGM. Targets for typical display materials like chromium, aluminium, molydaenium but also gold, nickel, palladium, ITO, AZO, IGZO are available. Numerous additional targets can be mounted as necessary. The sputter system can handle substrates of up to 16 inches squared. The first ZV6000 sputtering-system had been fundamentally refurbished in 2017. In 2020, together with the company HS-Group GmbH, we had been able to perform the modernization of the second sputtering-system as well. Now, both systems are state-of-the-art regarding to PLC system control, user interface, gasflow control, pressure measurement/-control and substrate transport drive. This enables new possibilities for deposition process optimization and allows for a long term perspective of operating the machines.
- Vapor Deposition: The IGM offers access to a Lesker Spectros vapor deposition system with two separate sources for metallic material and eight sources for organic material. The system is integrated into the inertgas glove boxes to enable oxygen and moisture free handling of OTFTs and OLEDs. In addition, the IGM features two older Balzers systems with thermal and electron beam vaporization systems. All vapor deposition systems can handle substrates of up to 6 inches squared.
- **Spin Coating:** The IGM operates several spin coaters for the deposition of photo resist and other liquids onto substrates of up to 16 inch squared. One smaller spin coater for substrates of up to 6 inches squared is integrated into the inert-gas glove boxes.
- Printing: Several printers for the direct deposition of structured layers are
 accessible at the IGM. Screen printers allow the large area deposition of
 material at a high volume but require a specifically made screen as a
 mask. A Dimatix inkjet printer can deposit almost any solution or
 suspension without the need for a complex physical mask. Additionally,
 the XTPL DELTA Ultra-Precise Deposition (UPD) printing system enables
 digital printing of highly precise patterns with linewidths below five microns
 at simultaneously high film thicknesses of several hundred nanometers.
 This allows for many new applications in the field of printed electronics,
 packaging or defect repair in thinfilm circuitry.

Photo Lithography

 Lithography with Photo Masks: The IGM is equipped with two contact exposure systems of type Süss MA6 for processing substrates of up to 6 inches squared. This allows for the realization of structures down to 3µm. • **Direct Imaging:** The IGM features a Heidelberg Instruments DWL 400 direct imaging system that can realize structures down to 2µm on 16 inch squared substrates without requiring complex photo masks.

Layer Modification

- Ion Implantation: Access to an ion implantor type Eaton (Axcelis) NV3206 is offered at the IGM. The standard airlock has been replaced with a larger one allowing the processing of substrates up to 16 inches squared. The system can implant phosphorus, boron, fluor, and argon ions at up to 200kV.
- Excimer-Laser: A Sopra VEL Excimer Laser for the recrystallization of amorphous into polycrystalline silicon is available at the IGM. The XeCl laser operates at a wavelength of 308nm and can fire 200ns pulses of up to 15J each at a target area of 67mm by 27mm. It can also be used to activate doping or to improve the crystal quality of other semiconductors. The system can process substrates of up to 16 inches squared using stitching.
- **UV-Ozone Treatment:** The IGM features a UV-Ozone system to clean substrates or to improve surface adhesion. The combination of highly reactive ozone and high energy light can remove organic contaminants and can activate the surface by freeing chemical bonds in surface molecules. The system can process substrates of up to 16 inches squared.

Liquid Crystal Technology

- **Rubbing:** The IGM offers access a Hörnell Rubbing system to structure the polyimide orientation layer by rubbing with a velvet roll.
- Spacer Spray System: The IGM operates an electrostatic spacer spray system type Accudyne for 5µm spherical polymer spacer used to ensure a uniform thickness of the liquid crystal cell. Additional different sizes of spacers can be sprayed or spin coated.
- **Glue Robot:** A Schiller 3-axis (xyz) gantry robot is used to apply glue frames in the assembly of the two substrates into one liquid crystal cell.
- **Filling Chamber:** The IGM utilizes a dedicated Balzers vacuum chamber with a movable substrate holder to fill cells with liquid crystals.
- **Cell Construction:** The IGM featurs a wide array of additional tools supporting the micrometer alignment of sustrates.

All of the above systems can handle substrates of up to 16 inches squared.

Metrology

- Waferprober: A Süss wafer prober in combination with a Keithley 4100 semi conductor measurement system allows for the reliable characterization of TFTs and other semiconductor electronic elements. Additional picoampere meters allow measurements in the clean room, in climate boxes and in intert-gas boxes.
- Viewing Angle Contrast Measuremen: An Eldim EZ Contrast 160 system is used for high-speed measurements of luminance, contrast and color space of transmissive and reflective or self-illuminating displays both in absolute values and their viewing angle dependency.
- **Climate Chamber:** A climate chamber allows for the controlled exposure to precisely definite environments, facilitating the evaluation of systems under different conditions and the simulated aging at increased environmental temperatures.
- **Optical Microscopes:** Several optical microscopes allow for quick inspections of processed substrates. Substrates of up to 16 inches squared can be checked.
- Scanning Electron Microscope: For inspections at resolutions above the limits of optical microscopes the IGM features a JEOL JSM 6100 SEM. This system has been modified for digital image generation.
- Atomic Force Microscope: The IGM features a DME AFM to determine surface topologies and surface roughness of layers.

Bonding

- **TAB Bonder:** Several TAB (Tape Automated Bonding) devices, both manual and semi-automatic, are available for bonding chips on foil (COF) driver chips onto glas substrates using anisotropically conductive adhesive film.
- Flip-Chip Bonder: Unmounted silicon chips can be bonded upside-down (flip-chip) directly onto display glas. This technique saves space on the substrate and is therefore well suited to tablet and smartphone displays. The IGM operates a Süss flip-chip bonder.

10 IGM-Activities

10.1 6G-LICRIS Workshop

Within the BMBF funded joint project 6G-LICRIS (Liquid Crystal Reconfigurable Intelligent Surfaces for 6G Mobile Networks), the Institute for Large Area Microelectronics (IGM) organized a workshop "Liquid Crystal Technology for High Frequency Applications" on April 28, 2023.

The aim was to explain assembly and principle of operation of liquid crystal cells to project partners as well as externals involved in the 6G-Platform. The IGM and MERCK held presentations on the topics "Fundamentals of Liquid Crystals", "Control of Liquid Crystals" and "Special Features for High Frequency Applications". At the end, the participants got a guided tour at the IGM, which gave them an interesting insight into the 480m² clean room lab.



Fig. 5: Participants of the 6G-LICRIS Workshop

10.2 Girls' Day

With the slogan "We want to show you that experimenting, doing research and building are not just for boys!", the IGM participated in the Girls' Day with the topic "Mobilephone, Laptop & Co., how does a display actually work". The Girls' Day of the University of Stuttgart was held on April 27, 2023.

The schoolgirls got an insight how a display works: from the light ray to the physics up to the control. Each element was demonstrated in a small practical experiment. The schoolgirls could perform some of the experiments by themselves, such as building their own touchpad prototype.

All participants had much fun and the Institute for Large Area Microelectronics was happy to get a lot of positive feed-back!

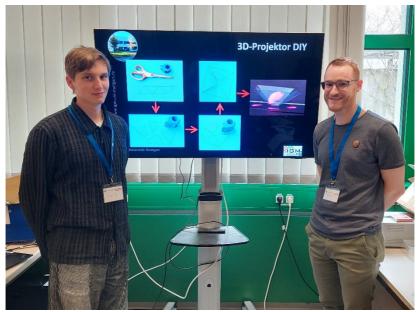


Fig. 6 Yannick Schellander and Kai Waldner explain how to build a 3D projector

10.3 Science Day

Once a year, the University of Stuttgart opens its laboratory doors and invites to a day full of discoveries and insights into the world of science.

On May 13, 2023 the IGM participated again in the Science Day and provided an insight into large area microelectronics, especially in the application fields of display and sensor technology, but also in the current research in mobile communications by presenting exhibits and demonstrations at its booth. Furthermore, the IGM offered guided tours at its institute, which generated lot of interest and gave the participants an exciting insight in its more than 500m² clean room area.



Fig. 7: Many visitors at the IGM booth

10.4 Institute Excursion

After a longer pause, the institute excursion could finally take place on July 19, 2023. In the morning we visited the Banksy Exhibition. After this very interesting exhibition we had a snack in the Koenigsbau Passagen in Stuttgart. Then, we took the subway to Stuttgart-Feuerbach and made a hiking tour to the sequoia and to the historic castle ruin Dischingen. The weather and mood were very good and at the end of the day we had a dinner on the terrace of the restaurant Gruenewald.



Fig. 8: IGM staff and students during the institute excursion

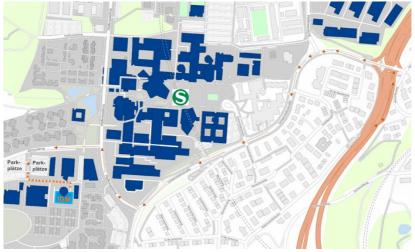
10.5 Christmas Party

The IGM invited "its" students and former employees to join the Christmas Party on December 18, 2023 in the premises of the institute. In a cozy atmosphere the participants enjoyed coffee and cake while exchanging ideas on all kinds of topics.

11 Directions and Maps

By car

Leave the highway "Autobahn A8" at the interchange "Autobahnkreuz Stuttgart-Vaihingen" and take the A831 / B14 in the direction of Vaihingen. Leave the B14 after the tunnel (careful: speed trap!) at the exit "Universität". At the traffic light turn left. Stay on "Universitätsstrasse" and later turn right into "Pfaffenwaldring". Then turn left into "Allmandring". Take the first entrance on the left and park your car on the university parking place. Now you only need to walk a few steps to the Institute of Large Area Microelectronics (IGM).



Map 1: By car to the Institute of Large Area Microelectronics

By public transport

Upon arrival at Stuttgart Main Station move towards the lower platforms (S-Bahn, green "S" as a logo). If you do not have a valid ticket for the S-Bahn to "Universität/University" you will need to get a ticket at one of the red ticket machines located near the top of the escalators down to the lower platforms. You will need a one-zone ticket. Choose your language, press the "VVS button" and then "1 zone". You will now be asked to choose between a "single-ticket" (one-way ticket) or a "4-journey-ticket" (multi-ticket usable for four trips). The "4-journey-ticket" has to be devalued before entering the train (small orange boxes).

Take one of the below S-Bahn trains at platform 101:

- S1 direction Herrenberg
- S2 direction Filderstadt
- S3 direction Flughafen

The S-Bahn comes every 5 to 20 minutes, depending on the time of day. Alight at the stop "Universität/University" (about 10 minutes trip) and follow the way from the S-Bahn station to the Institute for Large Area Microelectronics (IGM). <u>Please find a detailed way description on our website.</u>

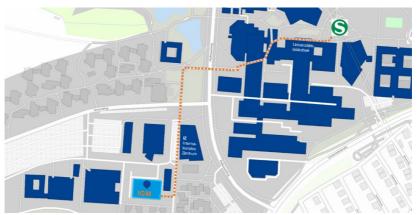
By plane

Upon arrival at the Stuttgart Airport you will exit the gate on level 1 (lower level). Go to the S-Bahn train station one level lower, marked with a large, green "S" logo. You will need to get a ticket at one of the red ticket machines located near the top of the escalators down to the lower platforms. You will need a two-zone ticket. Choose your language, press the "VVS button" and then "2 zones". You will now be asked to choose between a "single-ticket" (one-way ticket) or a "4-journey-ticket" (multi-ticket usable for four trips). The "4-journey-ticket" has to be devalued before entering the train (small orange boxes).

Take one of the below S-Bahn trains

- S2 direction Schorndorf
- S3 direction Backnang

and exit at S-Bahn station "Universität/University" (about 17 minutes trip). Then follow the way to the Institute for Large Area Microelectronics (IGM). Please find a detailed way description on our website.



Map 2: Sidewalk from S-Bahn station University to IGM

12 Contact

You can contact us at:

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